

2SB1026

Silicon PNP Epitaxial

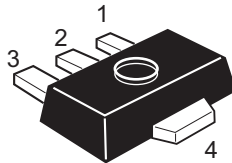
REJ03G0662-0200
(Previous ADE-208-1037)
Rev.2.00
Aug.10.2005

Application

- Low frequency power amplifier
- Complementary pair with 2SD1419

Outline

RENESAS Package code: PLZZ0004CA-A
(Package name: UPAK[®])



1. Base
2. Collector
3. Emitter
4. Collector (Flange)

*UPAK is a trademark of Renesas Technology Corp.

Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Ratings	Unit
Collector to base voltage	V _{CBO}	-120	V
Collector to emitter voltage	V _{CEO}	-100	V
Emitter to base voltage	V _{EBO}	-5	V
Collector current	I _C	-1	A
Collector peak current	i _{C(peak)} * ¹	-2	A
Collector power dissipation	P _C * ²	1	W
Junction temperature	T _J	150	°C
Storage temperature	T _{stg}	-55 to +150	°C

Notes: 1. PW ≤ 10 ms, Duty cycle ≤ 20%

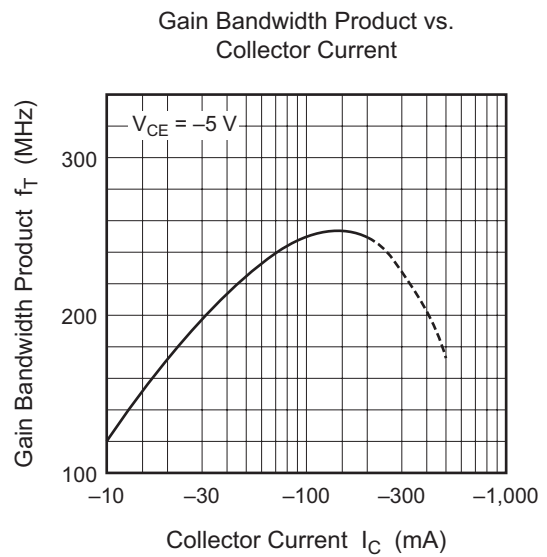
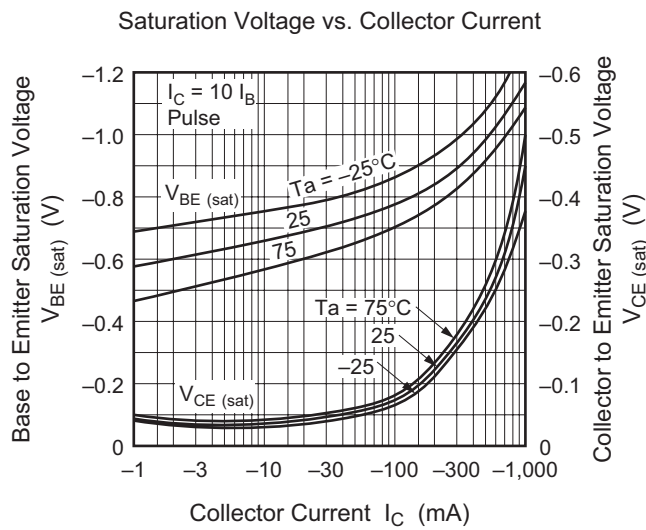
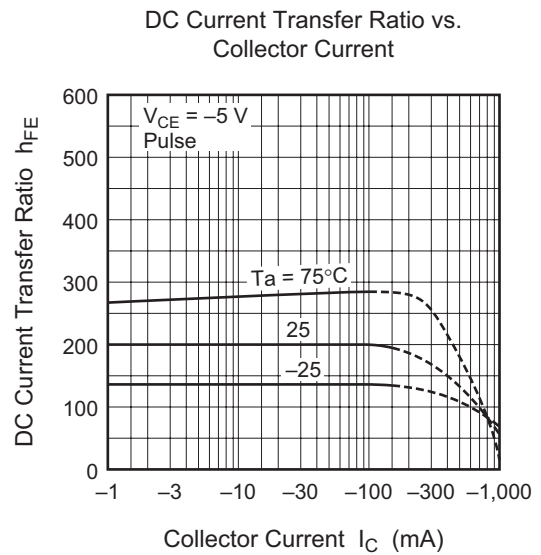
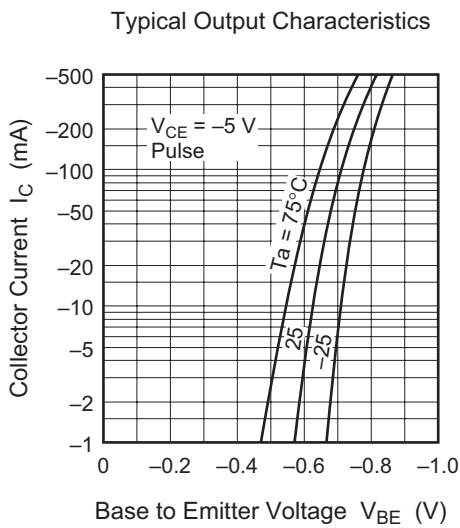
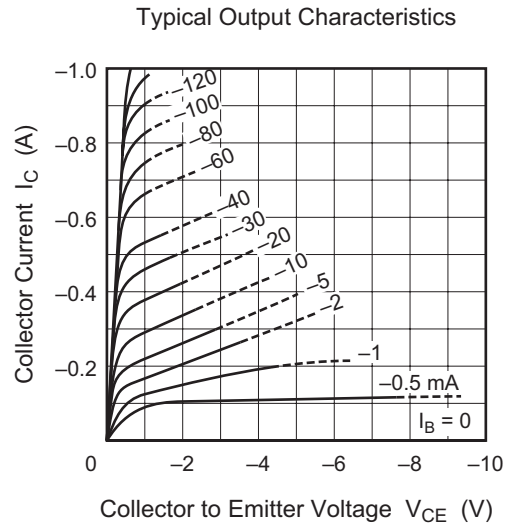
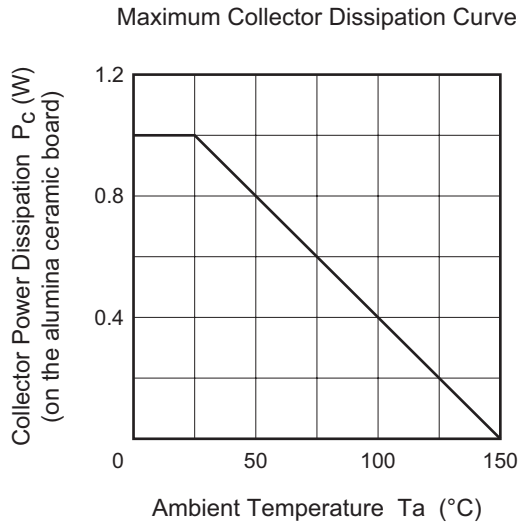
2. Value on the alumina ceramic board (12.5 × 20 × 0.7 mm)

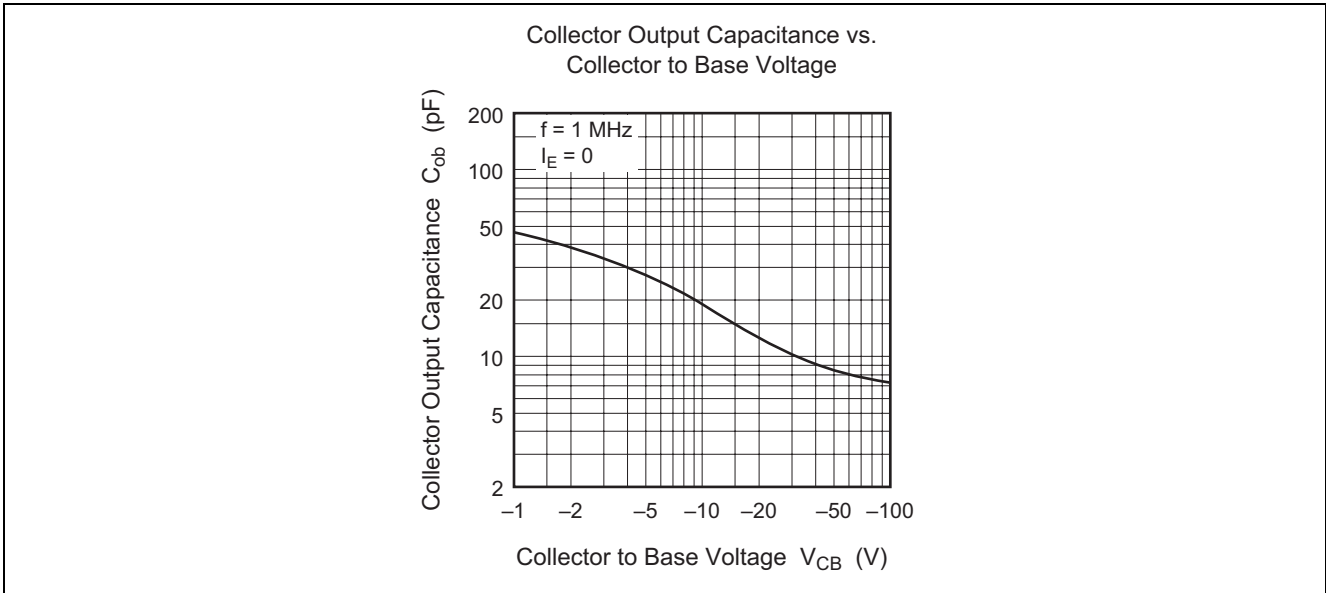
Electrical Characteristics

(Ta = 25°C)

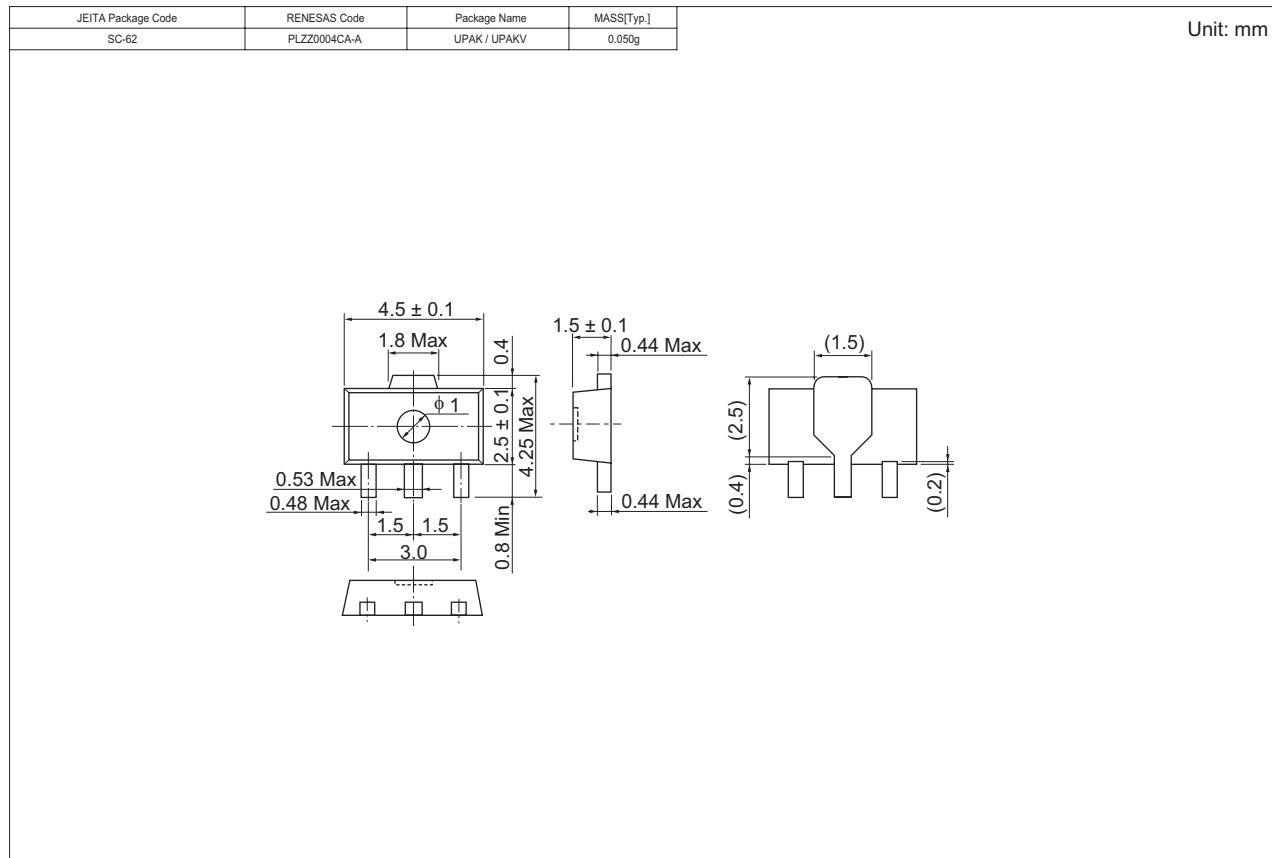
Item	Symbol	Min	Typ	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(BR)CBO}$	-120	—	—	V	$I_C = -10 \mu A, I_E = 0$
Collector to emitter breakdown voltage	$V_{(BR)CEO}$	-100	—	—	V	$I_C = -1 \text{ mA}, R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	-5	—	—	V	$I_E = -10 \mu A, I_C = 0$
Collector cutoff current	I_{CBO}	—	—	-10	μA	$V_{CB} = -100 \text{ V}, I_E = 0$
DC current transfer ratio	h_{FE1}	100	—	200		$V_{CE} = -5 \text{ V}, I_C = -150 \text{ mA}$
	h_{FE2}	30	—	—		$V_{CE} = -5 \text{ V},$ $I_C = -500 \text{ mA}$ (Pulse test)
Collector to emitter saturation voltage	$V_{CE(sat)}$	—	—	-1	V	$I_C = -500 \text{ mA},$ $I_B = -50 \text{ mA}$ (Pulse test)
Base to emitter voltage	V_{BE}	—	—	-0.9	V	$V_{CE} = -5 \text{ V}, I_C = -150 \text{ mA}$
Gain bandwidth product	f_T	—	140	—	MHz	$V_{CE} = -5 \text{ V}, I_C = -150 \text{ mA}$
Collector output capacitance	C_{ob}	—	20	—	pF	$V_{CB} = -10 \text{ V}, I_E = 0,$ $f = 1 \text{ MHz}$

Main Characteristics





Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
2SB1026DMTL-E	1000	ϕ 178 mm Reel, 12 mm Emboss Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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